



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP FF 12900 48p GbE SFP FX Mod(JH241A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing		0

radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
Socket spanner	M3

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the film 1;
2. Unscrew the screws on part 2, and then remove part 2;
3. Remove part 3 from part 2;
4. Unscrew the screws on heatsink 4, and then remove heatsink 4;
5. Unscrew the screws on part 5, and then remove part 5;
6. Unscrew the screws on pcb 6, and then remove pcb 6 from part 11;
7. Push part 7, and then remove part 7 and heatsink 8 from pcb 6;
8. Unscrew the screws on part 9, and then remove part 9 from pcb 6;
9. Unscrew the screws on part 10, and then remove part 10 from pcb 6.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

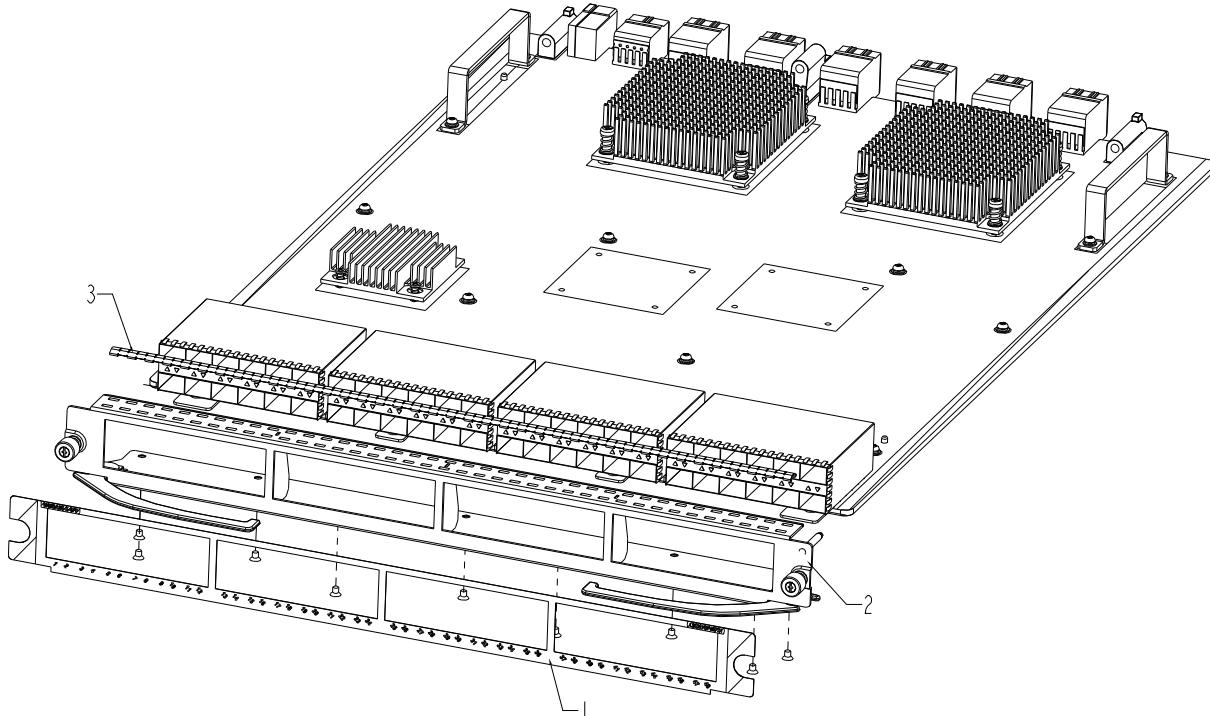


Figure 1 Treatments to the product

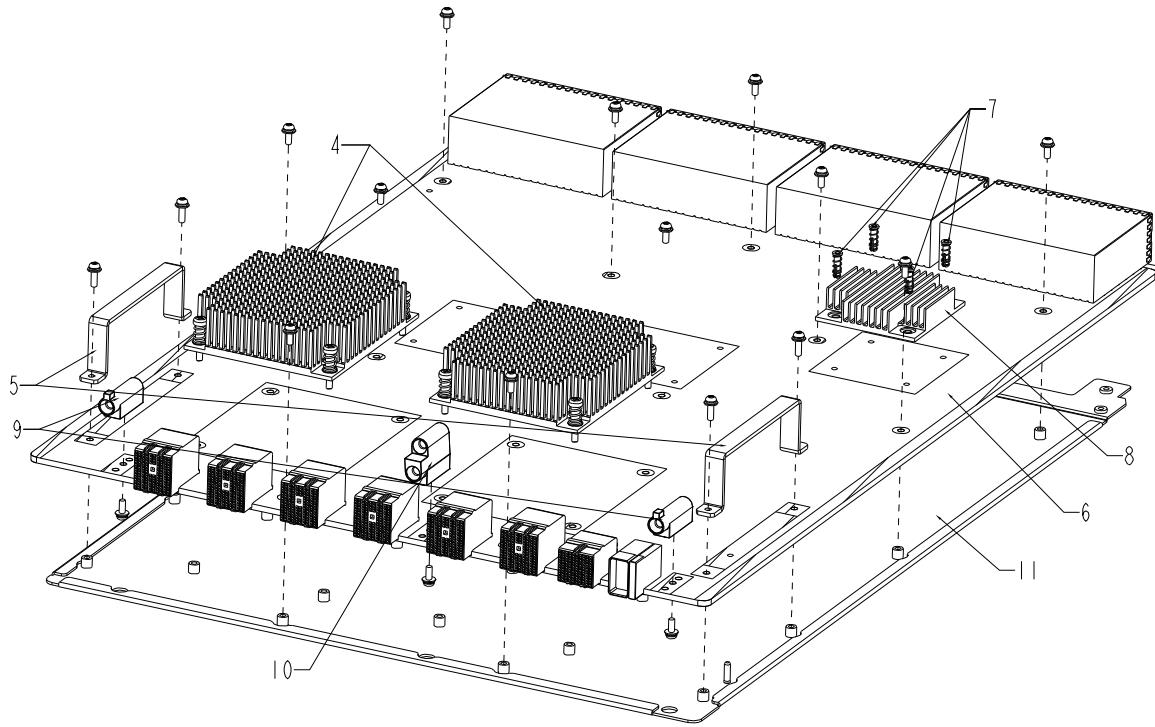


Figure 2 Treatments to the product

3.3 Material of the facility built

Facility	Components	Material	Weight(g) *PCS	Weight percentage	Selective treatment for materials and components	Details
1		Pla	1*1	0.02%		Pla recycling
2		Fe	347*1	7.26%		Fe recycling
3		Cu, Be	2*1	0.04%		Cu Be recycling
4		Al, Fe	170*2	7.12%		Al Fe recycling
5		Fe	24*2	1.00%		Fe recycling
6		Complex PCB	2231*1	46.69%	The surface of PCB is greater than 10 square centimeters;	
7		Pla, Fe	1*4	0.08%		Pla Fe recycling
8		Al	42*1	0.88%		Al recycling
9		Zn	16*2	0.67%		Zn recycling
10		Zn	30*1	0.63%		Zn recycling
11		Fe	1701*1	35.60%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2015.05.06	V0	Chen linwei	Initial version